

Features

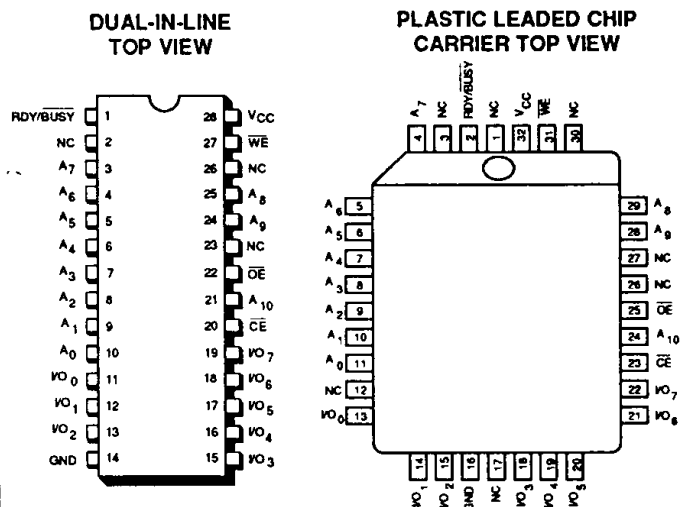
- **Military Extended and Commercial Temperature Range**
 - -55° C to +125° C Operation (Military)
 - -40° C to +85° C Operation (Extended)
 - 0° C to +70° C Operation (Commercial)
- **End of Write Detection**
 - Read Busy Pin
 - Optional DATA Polling Feature
- **High Endurance, Write Cycles**
 - 2817A: 10,000 Cycles/Byte Minimum
 - 5517A: 100K, 400K and 1 Million Cycles/Byte
- **On-Chip Timer**
 - Automatic Byte Erase Before Byte Write
- **5 V ± 10% Power Supply**
- **Power Up/Down Protection Circuitry**
- **150 ns max. Access Time**
- **Low Power Operation**
 - 100 mA Active Current
 - 40 mA Standby Current
- **JEDEC Approved Byte-Wide Pinout**
- **MIL-STD-883 Class B Compliant**

Description

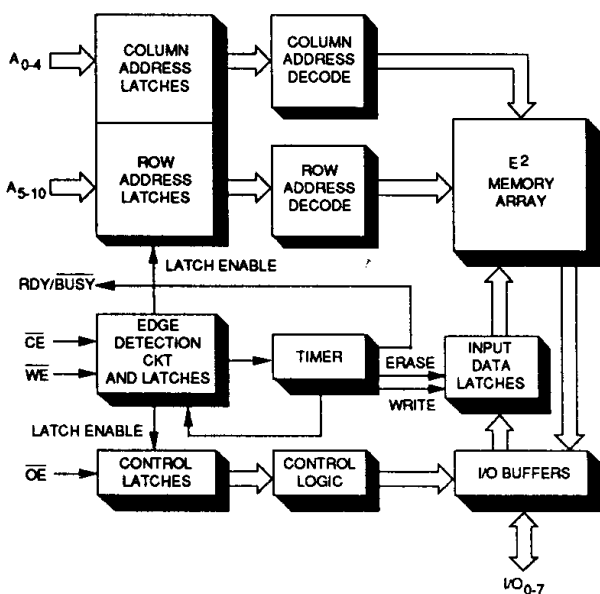
SEEQ's 2817A/5517A are 5V only, 2K x 8 electrically erasable programmable read only memory (EEPROM). They are packaged in 28 pin ceramic DIP and plastic DIP packages and a 32 pin leaded chip carrier, all with a ready/busy pin. This EEPROM is ideal for applications which require non-volatility and in-system data modification. The endurance, the minimum number of times which a byte may be written, is 10 thousand (K) cycles for the 2817A or 100K, 400K or 1 million cycles for the 5517A.

The 2817A has an internal timer that automatically times out the write time. The on-chip timer, along with the input

Pin Configuration



Block Diagram



Pin Names

| | |
|---------------------------------|---|
| A ₀ -A ₄ | ADDRESSES — COLUMN (LOWER ORDER BITS) |
| A ₅ -A ₁₀ | ADDRESSES — ROW |
| \overline{CE} | CHIP ENABLE |
| \overline{OE} | OUTPUT ENABLE |
| \overline{WE} | WRITE ENABLE |
| I/O ₀₋₇ | DATA INPUT (WRITE OR ERASE) DATA OUTPUT (READ) |
| RDY/ \overline{BUSY} | DEVICE READY/ \overline{BUSY} |
| NC | NO CONNECT |

latches, frees the microcomputer system for other tasks during the write time. The standard 2817A/5517A write cycle time is 10 ms over the recommended range, while the 2817AH/5517AH is a fast 2ms. An automatic byte erase is performed before a byte operation is started. Once a byte has been written, the ready/busy pin signals the microprocessor that it is available for another write or a read cycle. All inputs are TTL for both the byte write and read mode. Data retention is specified for 10 years.

Device Operation

There are five operational modes (see Table 1) and, except for the chip erase mode⁽¹⁾, only TTL inputs are required. To write into a particular location, a TTL low is applied to the write enable (\overline{WE}) pin of a selected (\overline{CE} low) device. This, combined with output enable (\overline{OE}) being

high, initiates a write cycle. During a byte write cycle, addresses are latched on either the falling edge of \overline{CE} or \overline{WE} , whichever one occurred last. Data is latched on the rising edge of \overline{CE} or \overline{WE} , whichever one occurred first. The byte is automatically erased before data is written. While the write operation is in progress, the RDY/BUSY output is at a TTL low. An internal timer times out the required byte write time and at the end of this time, the device signals the RDY/BUSY pin to a TTL high. The RDY/BUSY pin is an open drain output and a typical 3K Ω pull-up resistor to V_{CC} is required. The pull-up resistor value is dependent on the number of OR-tied 2817A RDY/BUSY pins.

DATA Polling (Optional Feature)

DATA polling is a method of minimizing write times by determining the actual end-point of a write cycle. If a read is performed to any address while the device is still writing, it will present the ones-complement of the last byte written. When the device has completed its write cycle, a read from the last address written will result in valid data. Thus, software can simply read from the part until the last data byte written is read correctly. Timing for a DATA polling read is the same as a normal read.

**COMMENT: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.*

Mode Selection (Table 1)

| Mode/Pin | \overline{CE} | \overline{OE} | \overline{WE} | I/O | RDY/BUSY |
|---------------|-----------------|-----------------|-----------------|-------------------|----------|
| Read | V_{IL} | V_{IL} | V_{IH} | D_{OUT} | High Z |
| Standby | V_{IH} | X | X | High Z | High Z |
| Byte Write | V_{IL} | V_{IH} | V_{IL} | D_{IN} | V_{OL} |
| Write Inhibit | X | V_{IL} | X | High Z/ D_{OUT} | High Z |
| | X | X | V_{IH} | High Z/ D_{OUT} | High Z |

X: any TTL level

Recommended Operating Conditions

| | | 2817A/2817AH-150 | 2817A/2817AH-200 | 2817A/2817AH-250 | 2817A/2817AH-300 |
|-------------------------|------------|------------------|------------------|------------------|------------------|
| | | 5517A/5517AH-150 | 5517A/5517AH-200 | 5517A/5517AH-250 | 5517A/5517AH-300 |
| Temperature Range | Commercial | 0°C to +70°C | 0°C to +70°C | 0°C to +70°C | 0°C to +70°C |
| | Extended | -40°C to +85°C | -40°C to +85°C | -40°C to +85°C | -40°C to +85°C |
| | Military | -55°C to +125°C | — | -55°C to +125°C | -55°C to +125°C |
| V_{CC} Supply Voltage | | 5V \pm 10% | 5V \pm 10% | 5V \pm 10% | 5V \pm 10% |

Endurance and Data Retention

| Symbol | Parameter | Value | Units | Condition | |
|----------|-------------------|-----------|------------------------------|------------------------------|------------------------------|
| N | Minimum Endurance | 2817A | 10,000 | Cycles/Byte | MIL-STD 883 Test Method 1033 |
| | | 5517A | 100,000 | Cycles/Byte | |
| | | 400,000 | MIL-STD 883 Test Method 1033 | | |
| | | 1,000,000 | | | |
| T_{DR} | Data Retention | >10 | Years | MIL-STD 883 Test Method 1033 | |

Notes:

1. Chip Erase is an optional mode.
2. Characterized. Not tested.

SEEQ
Technology, Incorporated

MD400101/A

Absolute Maximum Stress Ratings*

Temperature
 Storage -65°C to +150°C
 Under Bias
 Military/Extended -65°C to +135°C
 Commercial -10°C to +80°C

D.C. Voltage applied to all Inputs or Outputs with respect to ground +6.0 V to -0.5 V
 Undershoot/Overshoot pulse of less than 10 ns (measured at 50% point) applied to all inputs or outputs with respect to ground (undershoot) -1.0 V (overshoot) + 7.0 V

Power Up/Down Considerations

The 2817A/5517A has internal circuitry to minimize a false write during system V_{CC} power up or down. This circuitry prevents writing under any one of the following conditions.

1. V_{CC} is less than 3 V.⁽²⁾
2. A negative Write Enable (\overline{WE}) transition has not occurred with V_{CC} is between 3 V and 5 V.

Writing will also be prevented if \overline{CE} or \overline{OE} are in TTL logical states other than specified for a byte write in the Mode Selection table.

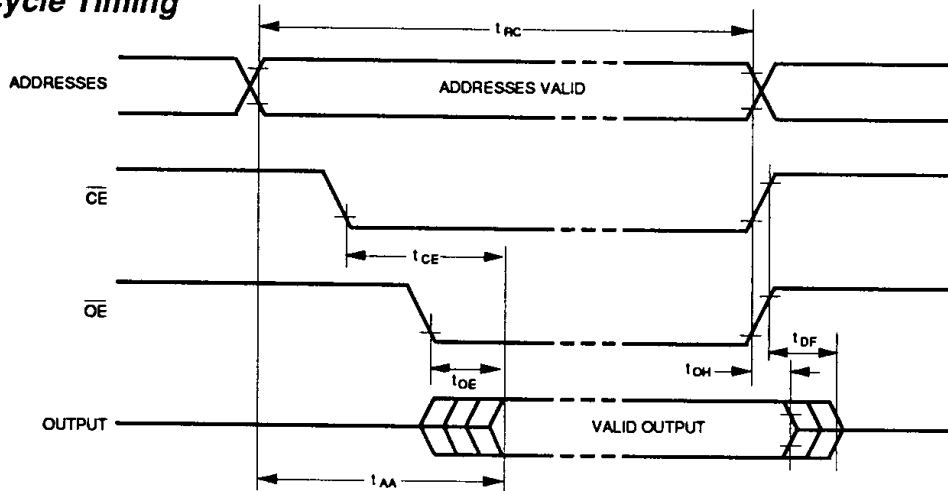
D.C. Operating Characteristics (Over the operating V_{CC} and temperature range)

| Symbol | Parameter | Limits | | Units | Test Condition |
|-----------------|---|--------|---------------------|-------|--|
| | | Min. | Max. | | |
| I _{CC} | Active V _{CC} Current (Includes Write Operation) | | 100 | mA | $\overline{CE} = \overline{OE} = V_{IL}$; All I/O Open; Other Inputs = 5.5 V |
| I _{SB} | Standby V _{CC} Current | | 40 | mA | $\overline{CE} = V_{IH}$, $\overline{OE} = V_{IL}$; All I/O Open; Other Inputs = 5.5 V |
| I _{LI} | Input Leakage Current | | 10 | μA | V _{IN} = 5.5 V |
| I _{LO} | Output Leakage Current | | 10 | μA | V _{OUT} = 5.5 V |
| V _{IL} | Input Low Voltage | -0.1 | 0.8 | V | |
| V _{IH} | Input High Voltage | 2.0 | V _{CC} + 1 | V | |
| V _{OL} | Output Low Voltage | | 0.4 | V | I _{OL} = 2.1 mA |
| V _{OH} | Output High Voltage | 2.4 | | V | I _{OH} = -400 μA |

A.C. Characteristics Read Operation (Over the operating V_{CC} and temperature range)

| Symbol | Parameter | Limits | | | | | | | | Units | Test Conditions |
|-----------------|---|--|------|--|------|--|------|--|------|-------|---|
| | | 2817A/ 2817AH-150 5517A/ 5517AH-150 | | 2817A/ 2817AH-200 5517A/ 5517AH-200 | | 2817A/ 2817AH-250 5517A/ 5517AH-250 | | 2817A/ 2817AH-300 5517A/ 5517AH-300 | | | |
| | | Min. | Max. | Min. | Max. | Min. | Max. | Min. | Max. | | |
| t _{RC} | Read Cycle Time | 150 | | 200 | | 250 | | 300 | | ns | $\overline{CE} = \overline{OE} = V_{IL}$ |
| t _{CE} | Chip Enable Access Time | | 150 | | 200 | | 250 | | 300 | ns | $\overline{OE} = V_{IL}$ |
| t _{AA} | Address Access Time | | 150 | | 200 | | 250 | | 300 | ns | $\overline{CE} = \overline{OE} = V_{IL}$ |
| t _{OE} | Output Enable Access Time | | 70 | | 90 | | 90 | | 100 | ns | $\overline{CE} = V_{IL}$ |
| t _{DF} | Output Enable High to Output Not being Driven | | 50 | | 60 | | 60 | | 60 | ns | $\overline{CE} = V_{IL}$ |
| t _{OH} | Output Hold from Address Change, Chip Enable, or Output Enable whichever occurs first | 0 | | 0 | | 0 | | 0 | | ns | \overline{CE} or $\overline{OE} = V_{IL}$ |

Read Cycle Timing



AC Characteristics

Write Operation (Over the operating V_{CC} and temperature range)

| Symbol | Parameter | Limits | | | | | | | | Units | |
|----------------|---------------------------------------|--|------|--|------|--|------|--|------|---------|----|
| | | 2817A/ 2817AH-150 5517A/ 5517AH-150 | | 2817A/ 2817AH-200 5517A/ 5517AH-200 | | 2817A/ 2817AH-250 5517A/ 5517AH-250 | | 2817A/ 2817AH-300 5517A/ 5517AH-300 | | | |
| | | Min. | Max. | Min. | Max. | Min. | Max. | Min. | Max. | | |
| t_{AS} | Address to Write Set Up Time | 10 | | 10 | | 10 | | 10 | | ns | |
| t_{CS} | \overline{CE} to Write Set Up Time | 10 | | 10 | | 10 | | 10 | | ns | |
| $t_{WP}^{[2]}$ | \overline{WE} Write Pulse Width | 100 | | 120 | | 150 | | 150 | | ns | |
| t_{AH} | Address Hold Time | 70 | | 50 | | 50 | | 50 | | ns | |
| t_{DS} | Data Set Up Time | 50 | | 50 | | 50 | | 50 | | ns | |
| t_{DH} | Data Hold Time | 0 | | 0 | | 0 | | 0 | | ns | |
| t_{CH} | \overline{CE} Hold Time | 0 | | 0 | | 0 | | 0 | | ns | |
| t_{OES} | \overline{OE} Set Up Time | 10 | | 10 | | 10 | | 10 | | ns | |
| t_{OEH} | \overline{OE} Hold Time | 10 | | 10 | | 10 | | 10 | | ns | |
| t_{DL} | Data Latch Time | 50 | | 50 | | 50 | | 50 | | ns | |
| $t_{DV}^{[3]}$ | Data Valid Time | | 1 | | 1 | | 1 | | 1 | μ s | |
| t_{DB} | Time to Device Busy | | 120 | | 120 | | 120 | | 120 | ns | |
| t_{WR} | Write Recovery Time Before Read Cycle | | 10 | | 10 | | 10 | | 10 | μ s | |
| t_{WC} | Byte Write Cycle Time | | | | | | | | | | |
| | | 2817A/5517A | | 10 | | 10 | | 10 | | 10 | ms |
| | | 2817AH/5517AH | | 2 | | 2 | | 2 | | 2 | ms |

NOTES:

1. This parameter is measured only for the initial qualification and after process or design changes which may affect capacitance.
2. \overline{WE} is noise protected. Less than a 20 ns write pulse will not activate a write cycle.
3. Data must be valid within 1 μ s maximum after the initiation of a write cycle.

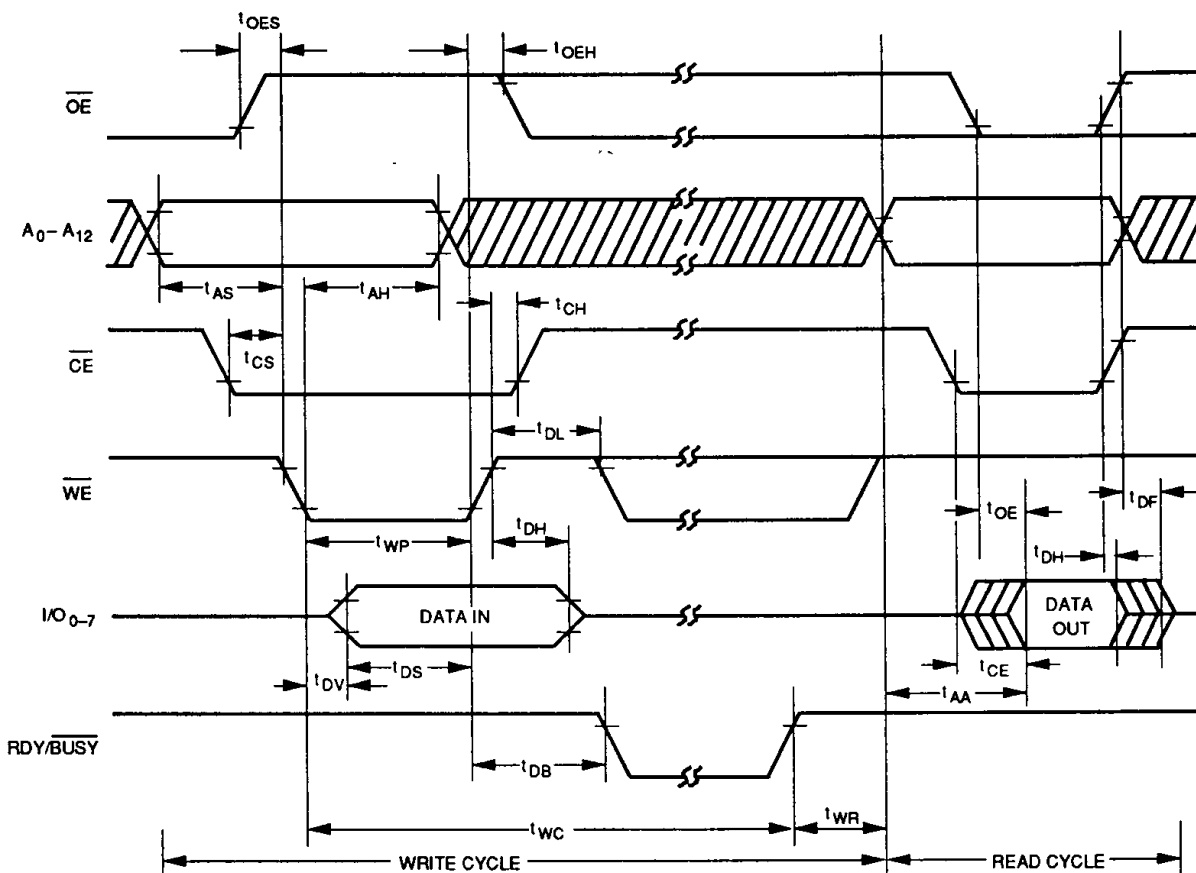
A.C. Test Conditions

Output Load: 1 TTL gate and $C_L = 100$ pF
 Input Rise and Fall Times: < 20 ns
 Input Pulse Levels: 0.45 V to 2.4 V
 Timing Measurement Reference Level:
 Inputs 1 V and 2 V
 Outputs 0.8 V and 2 V

Capacitance ⁽¹⁾ $T_A = 25^\circ\text{C}$, $f = 1$ MHz

| Symbol | Parameter | Max | Conditions |
|-----------|------------------------|-------|-----------------|
| C_{IN} | Input Capacitance | 6 pF | $V_{IN} = 0$ V |
| C_{OUT} | Data (I/O) Capacitance | 10 pF | $V_{I/O} = 0$ V |

Write Cycle Timing



Ordering Information

